

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below. Please enter these claims as amended. This listing of claims will replace all prior versions and listings of claims in the application.

Please cancel claim 16 without prejudice or disclaimer.

Please amend claim 13 as set forth below.

Listing of Claims:

1-5. (Cancelled)

6. (Previously Presented) An integrated circuit package comprising:
a semiconductor die;
a lead frame including a plurality of conductors, at least some of which are coupled to the semiconductor die;
at least one alignment feature formed in the lead frame separate from the conductors and configured to facilitate positive alignment of the integrated circuit package with an external structure; and
insulating material encompassing the semiconductor die and the at least one alignment feature, the insulating material being bound by a peripheral edge, wherein the at least one alignment feature is formed and encompassed along the peripheral edge.

7. (Previously Presented) The integrated circuit package of claim 6, wherein the at least one alignment feature is an alignment cut out.

8. (Cancelled)

9. (Previously Presented) The integrated circuit package of claim 6, wherein the at least one alignment feature is semicircular shaped.

10. (Original) The integrated circuit package of claim 6, wherein the at least one alignment feature comprises a tie bar.

11. (Previously Presented) The integrated circuit package of claim 6, wherein the lead frame includes a first end and a second end, wherein the at least one alignment feature comprises an alignment feature disposed on both the first end and the second end of the lead frame.

12. (Original) The integrated circuit package of claim 6, wherein the at least one alignment feature comprises a protuberance.

13. (Currently Amended) An integrated circuit package comprising:
a semiconductor die;
a lead frame including a plurality of conductors, at least some of which are coupled to the semiconductor die;
insulating material encompassing the semiconductor die and portions of the plurality of conductors; and
at least one alignment feature formed in a portion of the lead frame separate from the conductors, at least partially external to the insulating material and electrically isolated from the plurality of conductors wherein the at least one alignment feature is configured to be removable from the integrated circuit package.

14. (Cancelled)

15. (Original) The integrated circuit package of claim 6, wherein the at least one alignment feature is configured to be removable from the integrated circuit package.

16. (Cancelled)